



PATENT

Applicant: Gurtej Singh Sandhu et al.

Examiner: Kiesha L. Rose

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Title: CONDUCTIVE CONTAINER STRUCTURES HAVING A DIELECTRIC CAP

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents
Washington, D.C. 20231

This paper is in response to the Office Action mailed on September 5, 2002. Please amend the above-identified patent application as follows.

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IN THE SPECIFICATION

Please make the paragraph substitutions indicated in the appendix entitled Clean Version of Amended Specification Paragraphs. The specific changes incorporated in the substitute paragraphs are shown in the following marked-up versions of the original paragraphs:

Please amend the paragraph beginning at page 6, line 28 as follows:

Fill layer 50 and container layer 40 are then removed to approximately the top of insulating layer 15 in Figure 4. Fill layer 50 and container layer 40 are preferably planarized by chemical mechanical polishing (CMP) or removed by blanket etch-back. At this stage, a container structure is defined by a portion of container layer 40 formed on the sidewalls of the opening, and a closed bottom defined by a portion of container layer 40 formed on the bottom of the opening. Through continued removal, fill layer 50 and container layer 40 are then recessed (70) to just below the surface of insulating layer 15 in Figure 5. Such removal may be accomplished through CMP with chemistry more selective to fill layer 50 and container layer 40 than insulating layer 15, or by an etch-back process.

Please amend the paragraph beginning at page 8, line 28 as follows:

In an alternative embodiment, processing of the container structure 100 proceeds as in the previous embodiment through that depicted in Figure 4, where container layer 40 and fill layer 50 are removed to the surface of insulating layer 15. As shown in Figure 10, container layer 40 is